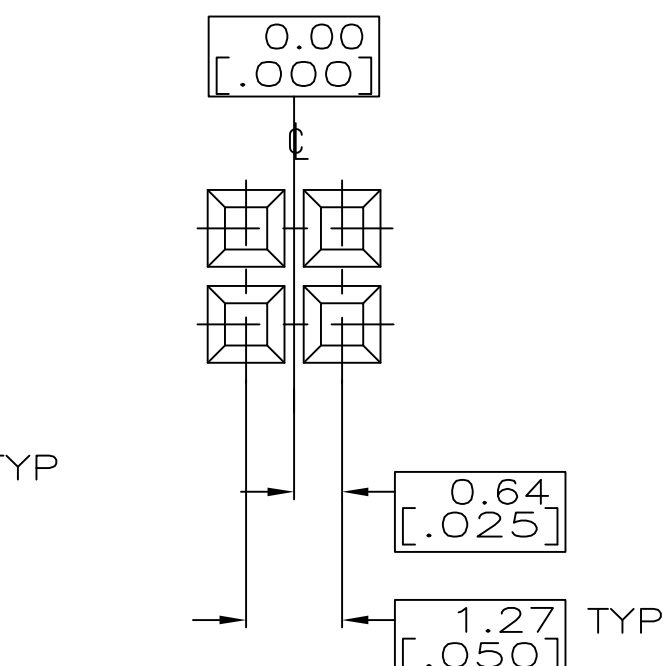
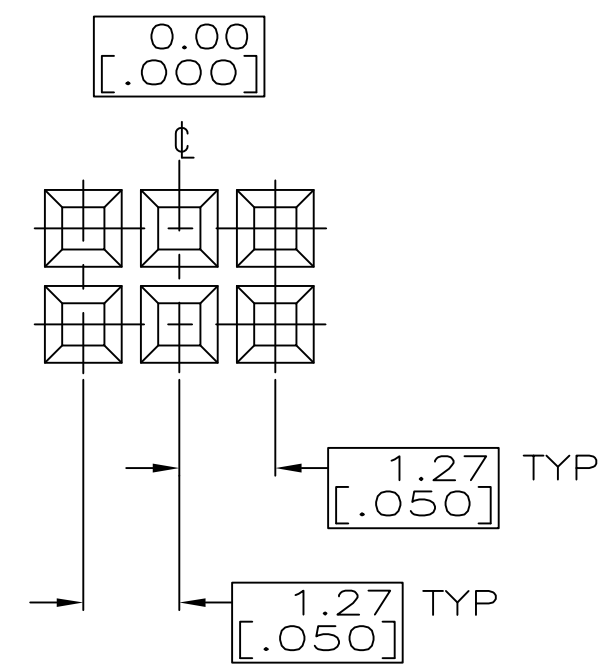
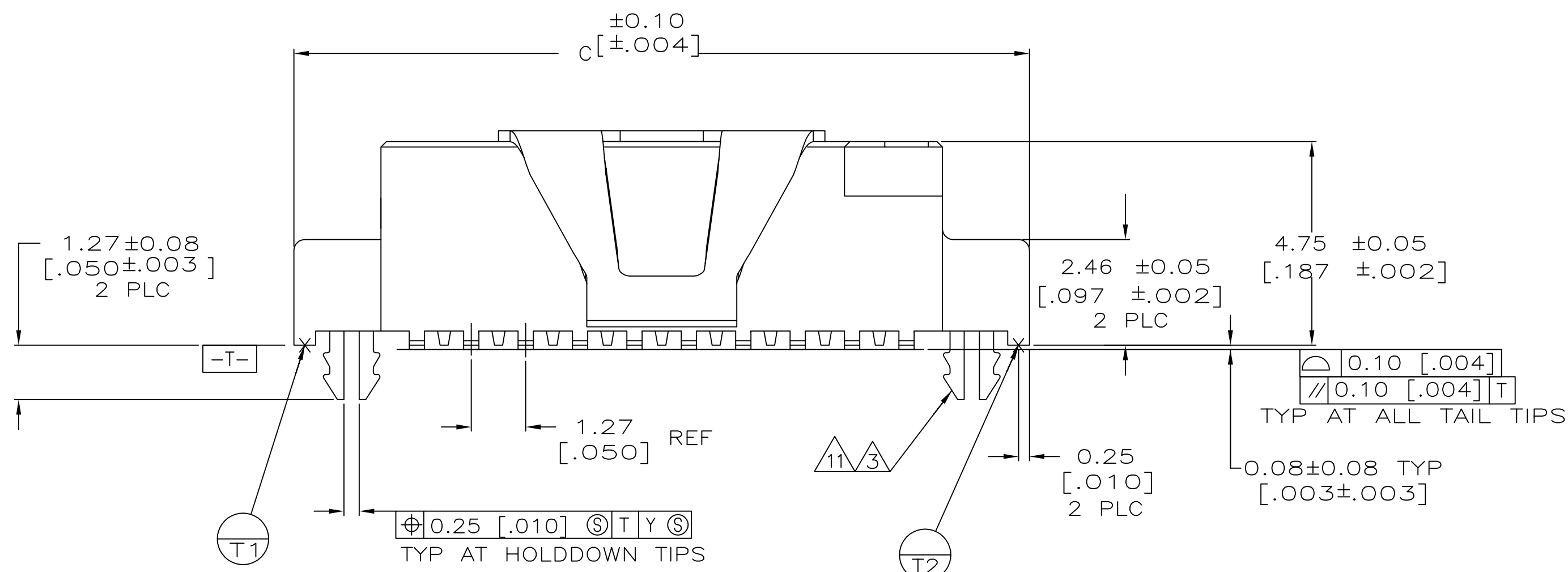
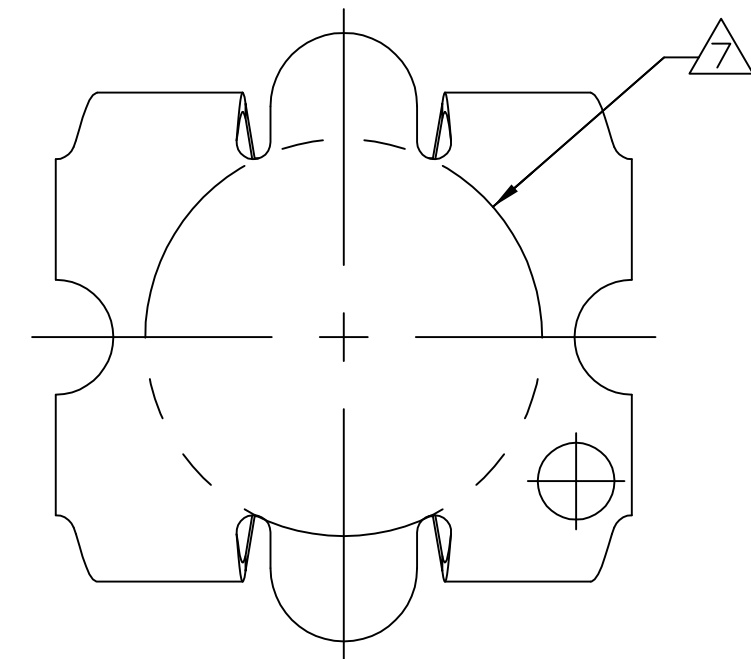
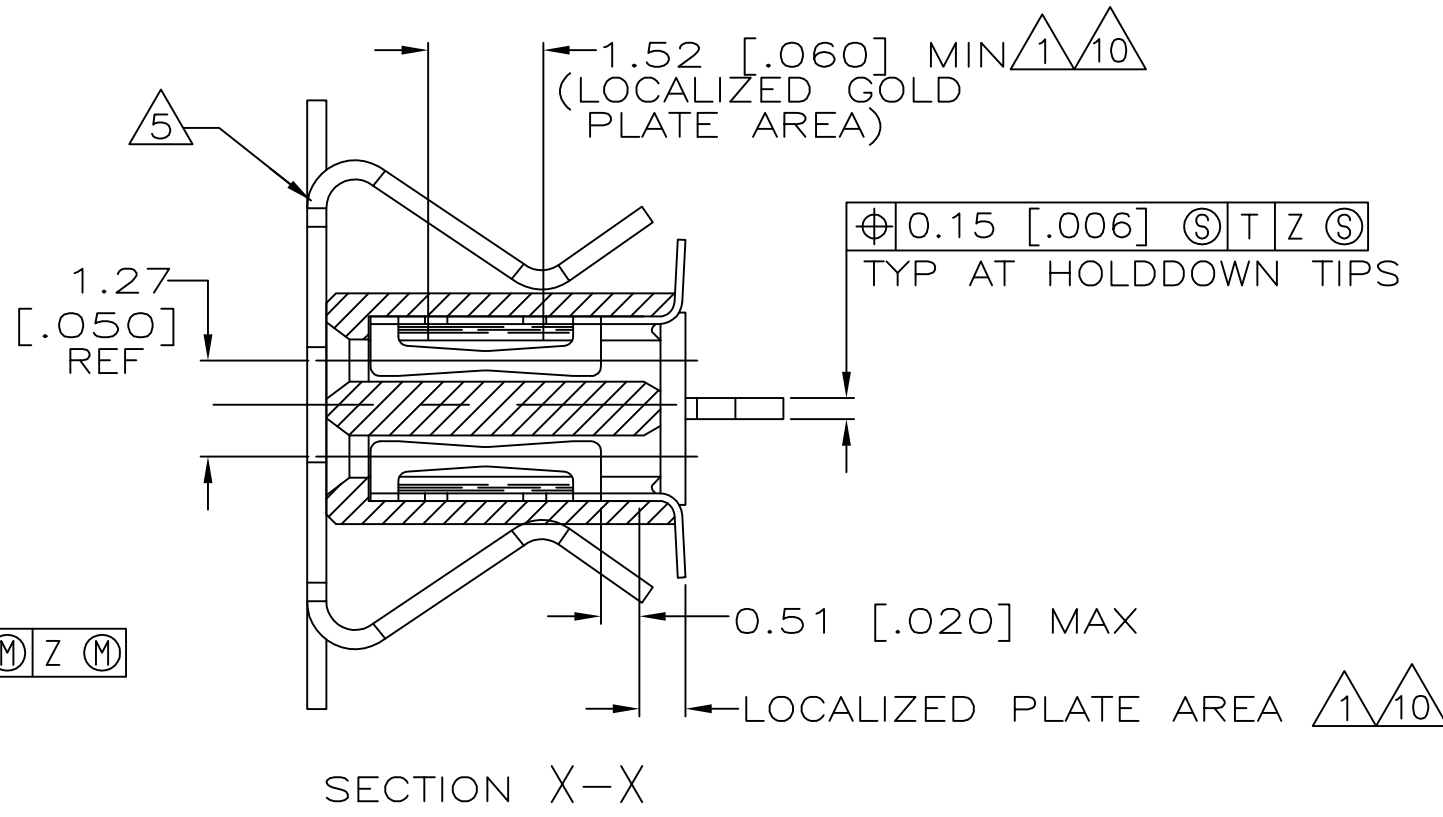
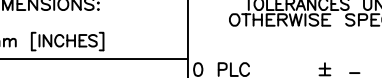




SCALE; 5:1

- 1 0.00076 [.000030] GOLD IN LOCALIZED PLATE AREA 0.00381 [.000150] TIN-LEAD ON SOLDER TAILS ALL OVER 0.00127 [.000050] NICKEL
- 2 USE 1.55±0.02 [.0610±.0010] DRILLED HOLE (1.55mm DRILL) FINISH TO BE TIN/LEAD OVER 0.02 [.001] MIN COPPER
- 3 PLATING: 0.0038 [.000150] TIN-LEAD OVER 0.00127 [.000050] NICKEL
- 4 IF PLANNING TO USE MORE THAN ONE MATING PAIR OF CONNECTORS TO INTERCONNECT 2 BOARDS, PLEASE REFER TO PARA. 3.3 IN THE APPLICATION SPEC, #114-7010
- 5 VACUUM COVER DESIGNED FOR 4.0 [.160] DIA NOZZLE. VACUUM COVER TO BE REMOVED AFTER SOLDERING.
- 6 PACKAGED IN EIA 481 TAPE AND REEL. SEE TABLE FOR TAPE WIDTHS.
- 7 5.2 [.205] MIN TARGET AREA FOR VACUUM PICK-UP.
- 8 HOUSING: LCP, COLOR-BLACK. CONTACT: COPPER ALLOY PER ASTM SPECIFICATION B422.
HOLDDOWN: COPPER ALLOY PER ASTM SPECIFICATION B194.
VACUUM COVER: ALUMINUM ALLOY PER ASTM SPECIFICATION B209.
- 9 VACUUM COVER SHOWN IN PHANTOM LINE.
- 10 0.00076 [.000030] GOLD IN LOCALIZED PLATE AREA 0.00381 [.000150] TIN ON SOLDER TAILS ALL OVER 0.00127 [.000050] NICKEL
- 11 PLATING: 0.0038 [.000150] TIN OVER 0.00127 [.000050] NICKEL
- 12 USE 1.55±0.02 [.0610±.0010] DRILLED HOLE (1.55mm DRILL) FINISH TO BE TIN OVER 0.02 [.001] MIN COPPER
- 13 OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN B. HAYMAKER	28JAN00	 TE Connectivity	
		CHK J. MOSIER	28JAN00		
DIMENSIONS: mm. [INCHES]		TOLERANCES UNLESS OTHERWISE SPECIFIED:		NAME	ASSY, RECEPTACLE, VRTCL.DOUBLE ROW, SRFC MOUNT,AMP/MODU 50/50 GRID CONNECTOR
		APVD J. MOSIER		PRODUCT SPEC	
		108-1332		APPLICATION SPEC	
		114-7010		SIZE: CAGE CODE: DRAWING NO: RESTRICTED TO:	
MATERIAL: 		WEIGHT: —		A1 00779 C=147384	SCALE: 1:0.1 SHEET 1 of 1 REV E
SEE TABLE		CUSTOMER DRAWING			

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